

GSM3153

30V P-Channel Enhancement Mode MOSFET

Product Description

GSM3153, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

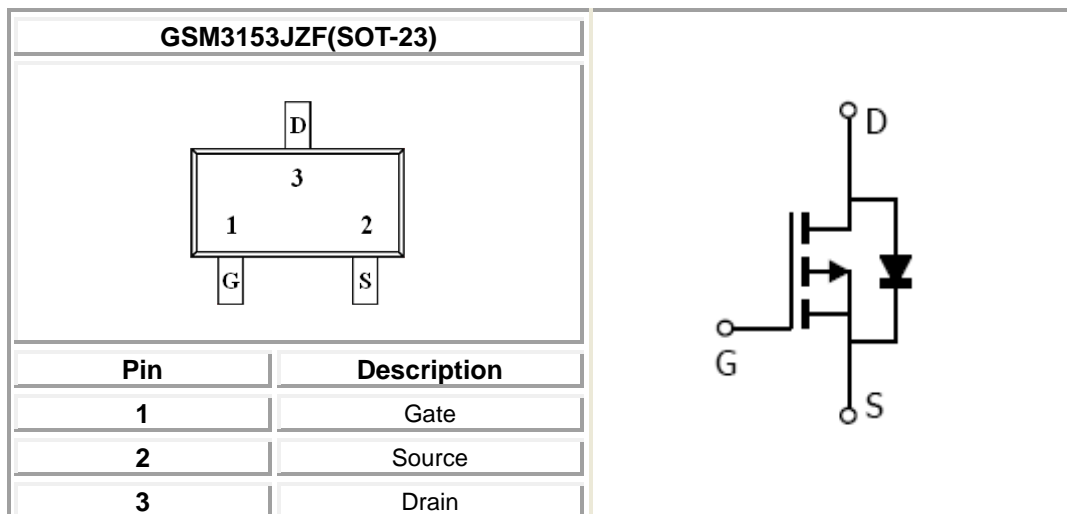
Features

- -30V/-4.8A $R_{DS(ON)}=54m\Omega@V_{GS}=-10V$
- -30V/-3.8A $R_{DS(ON)}=72m\Omega@V_{GS}=-4.5V$
- -30V/-3.0A $R_{DS(ON)}=120m\Omega@V_{GS}=-2.5V$
- Suit for -2.5V Gate Drive Applications

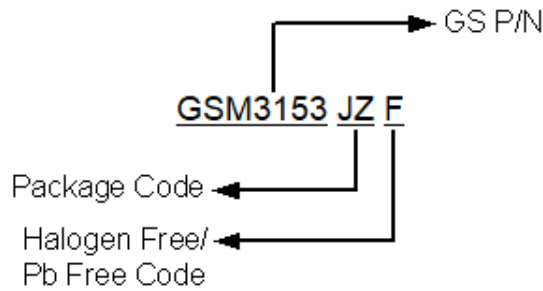
Applications

- Notebook
- LED Display
- DC-DC System
- LCD Panel

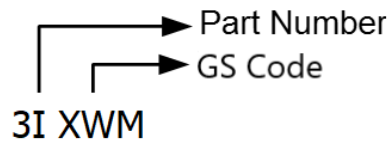
Packages & Pin Assignments



Ordering Information



Marking Information



Part Number	Package	Part Marking	Quantity
GSM3153JZF	SOT-23	3IXWM	3000PCS

Absolute Maximum Ratings

$T_A=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Typical	Unit
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current($T_J=150^{\circ}\text{C}$)	$T_A=25^{\circ}\text{C}$	-4.8
		$T_A=70^{\circ}\text{C}$	-3.8
I_{DM}	Pulsed Drain Current	-19	A
I_S	Continuous Source Current(Diode Conduction)	-1	A
P_D	Power Dissipation	$T_A=25^{\circ}\text{C}$	1.92
		$T_A=70^{\circ}\text{C}$	1.23
T_J	Operating Junction Temperature	150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55/150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient($t \leq 10\text{s}$)	65	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics

T_A=25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-0.7		-1.3	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±12V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-24V, V _{GS} =0V			-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =85°C			-30	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-10V, I _D =-4.8A		44	54	mΩ
		V _{GS} =-4.5V, I _D =-3.8A		62	72	
		V _{GS} =-2.5V, I _D =-3.0A		98	120	
V _{SD}	Diode Forward Voltage	I _S =-1.0A, V _{GS} =0V		-0.7	-1.0	V
Dynamic						
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz		573		pF
C _{oss}	Output Capacitance			74		
C _{rss}	Reverse Transfer Capacitance			53		
Q _g	Total Gate Charge	V _{DS} =-15V, V _{GS} =-10V, I _D =-4.8A		13.6		nC
Q _{gs}	Gate-Source Charge			1.2		
Q _{gd}	Gate-Drain Charge			2.0		
t _{d(on)}	Turn-On Time	V _{DD} =-15V, R _L =10Ω, I _D =-1.0A, V _{GEN} =-10V, R _G =6.0Ω		6.9		ns
T _r				12.3		
t _{d(off)}	Turn-Off Time			25		
T _f				13		

Typical Performance Characteristics

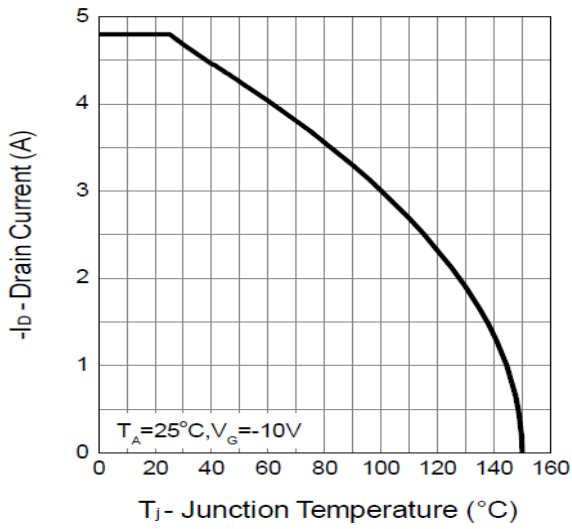


Figure 1. Drain Current vs. Temperature

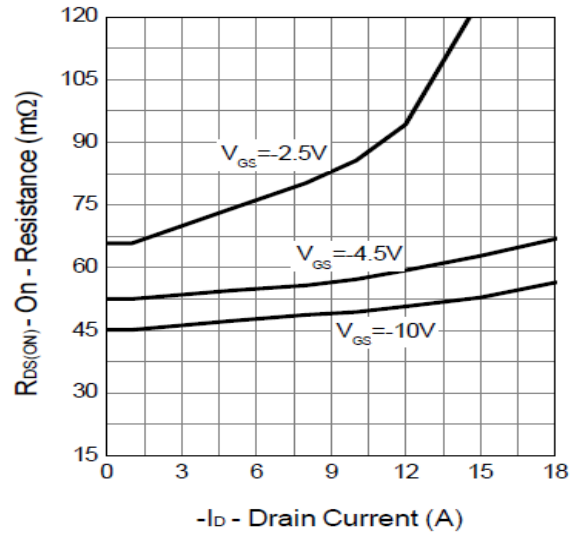


Figure 2. On-Resistance vs. Drain Current

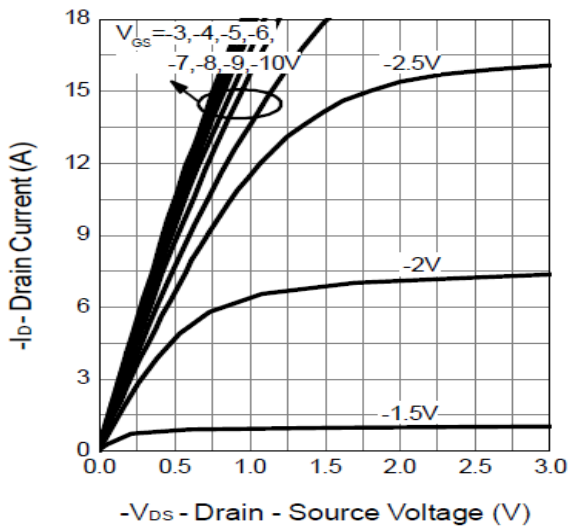


Figure 3. Output Characteristics

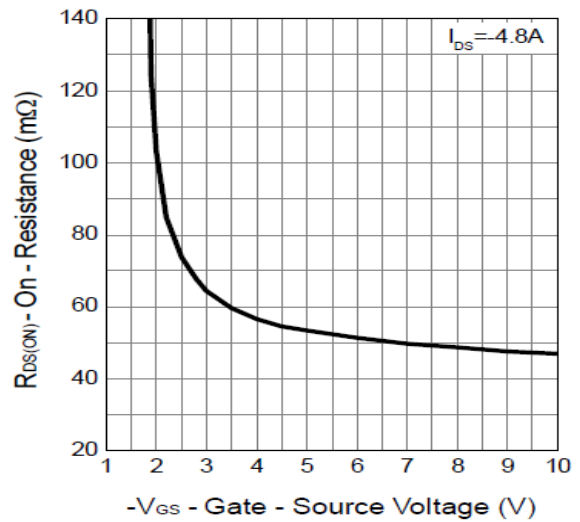


Figure 4. On-Resistance vs. Gate-Source Voltage

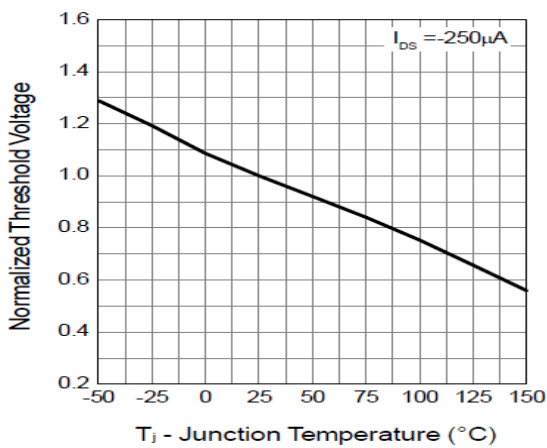


Figure 5. Threshold Voltage

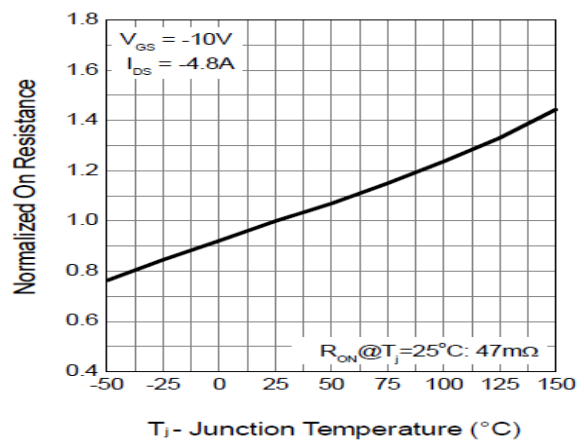


Figure 6. On-Resistance vs. Gate-Source Voltage

Typical Performance Characteristics (continue)

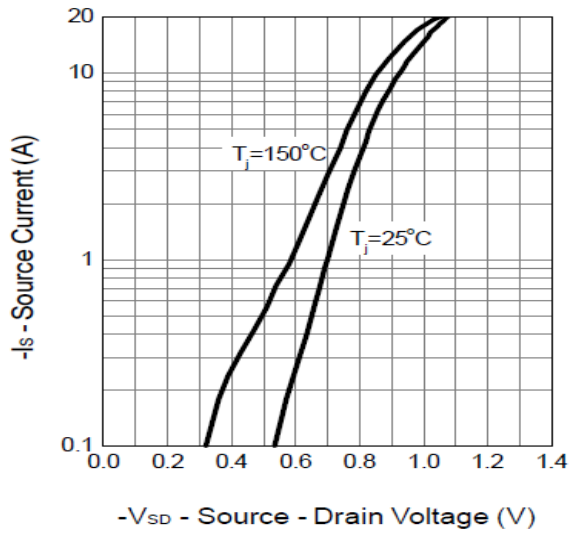


Figure 7. Source-Drain Diode Forward Voltage

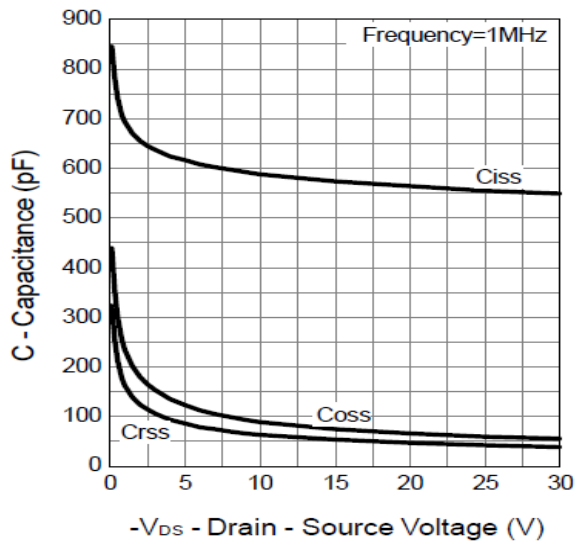


Figure 8. Capacitance

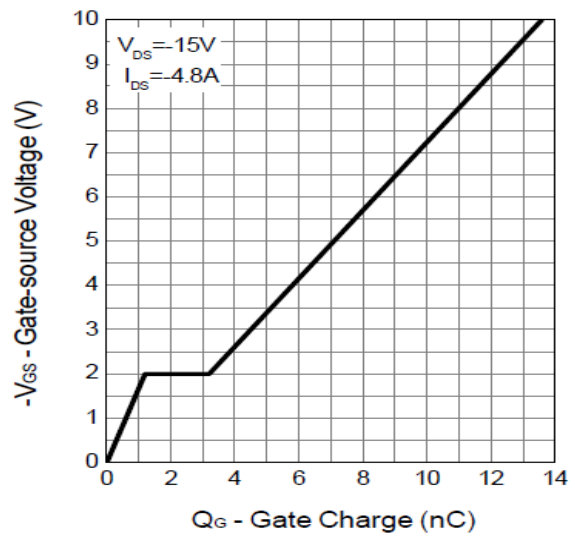


Figure 9. Gate Charge

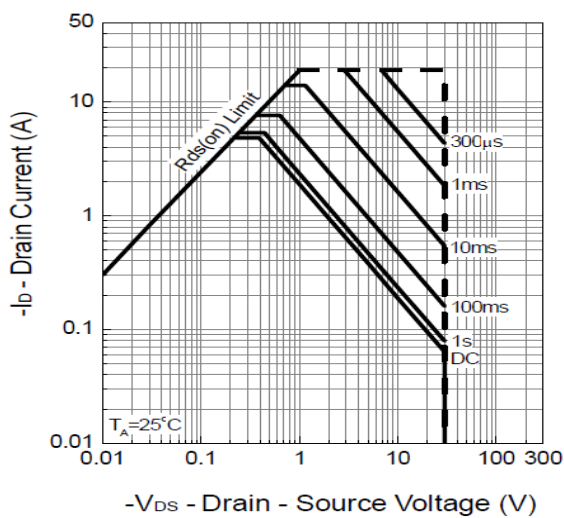


Figure 10. Safe Operation Area

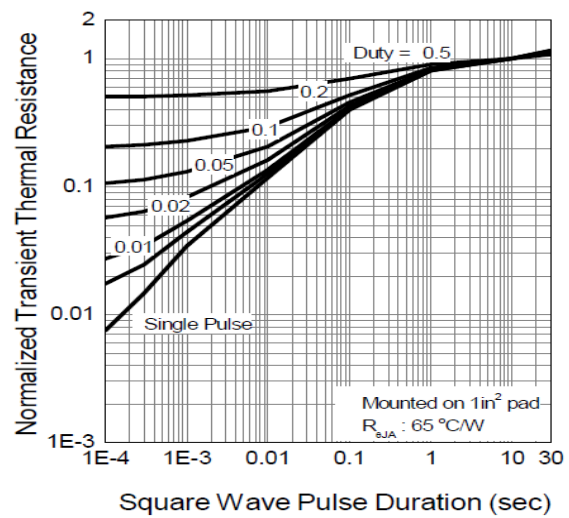
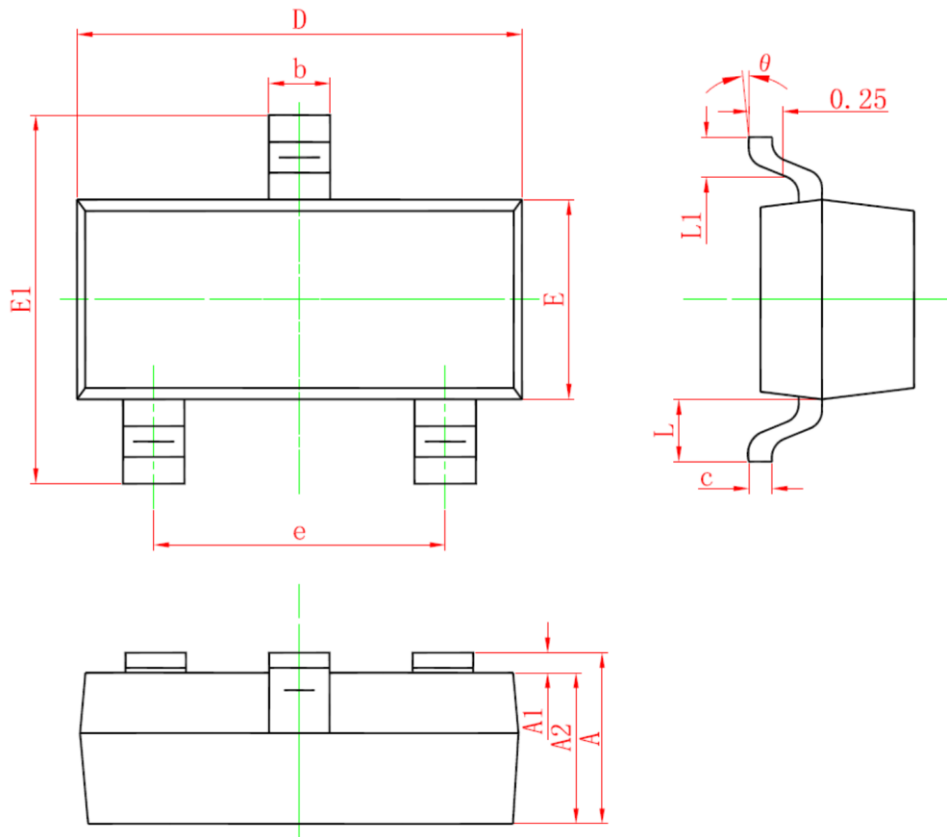


Figure 11. Normalized Thermal Transient Impedance

Package Dimension

SOT-23







Dimensions



SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.100	0.035	0.043
b	0.300	0.500	0.012	0.020
c	0.132	0.202	0.005	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

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CONTACT US

GS Headquarter	
	4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C)
	886-2-2657-9980
	886-2-2657-3630
	sales_twn@gs-power.com

RD Division	
	824 Bolton Drive Milpitas. CA. 95035
	1-408-457-0587